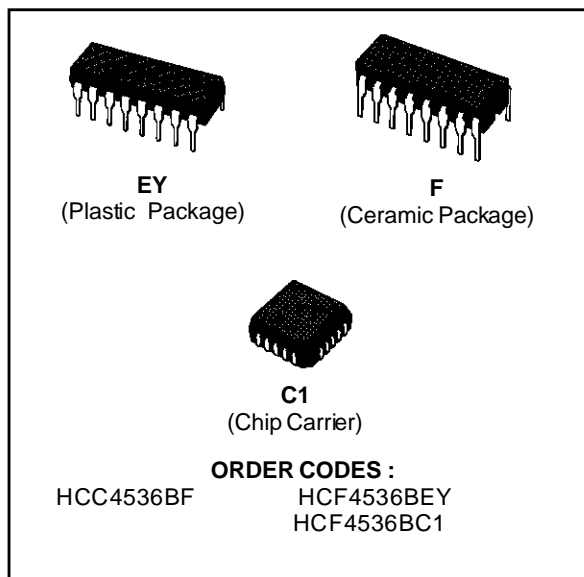


PROGRAMMABLE TIMER

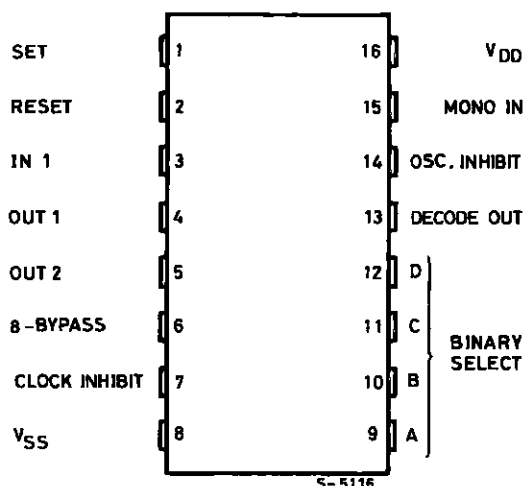
- 24 FLIP-FLOP STAGES - COUNTS FROM 2^0 TO 2^{24}
- LAST 16 STAGES SELECTABLE BY BCD SELECT CODE
- BYPASS INPUT ALLOWS BYPASSING FIRST 8 STAGES
- ON-CHIP RC OSCILLATOR PROVISION
- CLOCK INHIBIT INPUT
- SCHMITT-TRIGGER IN CLOCK LINE PERMITS OPERATION WITH VERY LONG RISE AND FALL TIMES
- ON-CHIP MONOSTABLE OUTPUT PROVISION
- TYPICAL $f_{CL} = 3\text{MHz}$ AT $V_{DD} = 10\text{V}$
- TEST MODE ALLOWS FAST TEST SEQUENCE
- SET AND RESET INPUTS
- CAPABLE OF DRIVING TWO LOW POWER TTL LOADS, ONE LOWER-POWER SCHOTTKY LOAD, OR TWO HTL LOADS OVER THE RATED TEMPERATURE RANGE
- STANDARDIZED, SYMMETRICAL OUTPUT CHARACTERISTICS
- QUIESCENT CURRENT AT 20V FOR HCC DEVICE
- 5V, 10V, AND 15V PARAMETRIC RATINGS
- INPUT CURRENT OF 100 nA AT 18V AND 25°C FOR HCC DEVICE
- 100% TESTED FOR QUIESCENT CURRENT
- MEETS ALL REQUIREMENTS OF JEDEC TENTATIVE STANDARD N^o. 13A, "STANDARD SPECIFICATIONS FOR DESCRIPTION OF "B" SERIES CMOS DEVICES"

DESCRIPTION

The **HCC4536B** (extended temperature range) and **HCF4536B** (intermediate temperature range) are monolithic integrated circuits, available in 16-lead dual in-line plastic or ceramic package. The **HCC/HCF4536B** is a programmable timer consisting of 24 ripple-binary counter stages. The salient feature of this device is its flexibility. The device can count from 1 to 2^{24} or the first 8 stages can be bypassed to allow an output, selectable by a 4-bit code, from any one of the remaining 16 stages. It can be driven by an external clock or an RC oscillator that can be constructed using on-chip components.



PIN CONNECTIONS

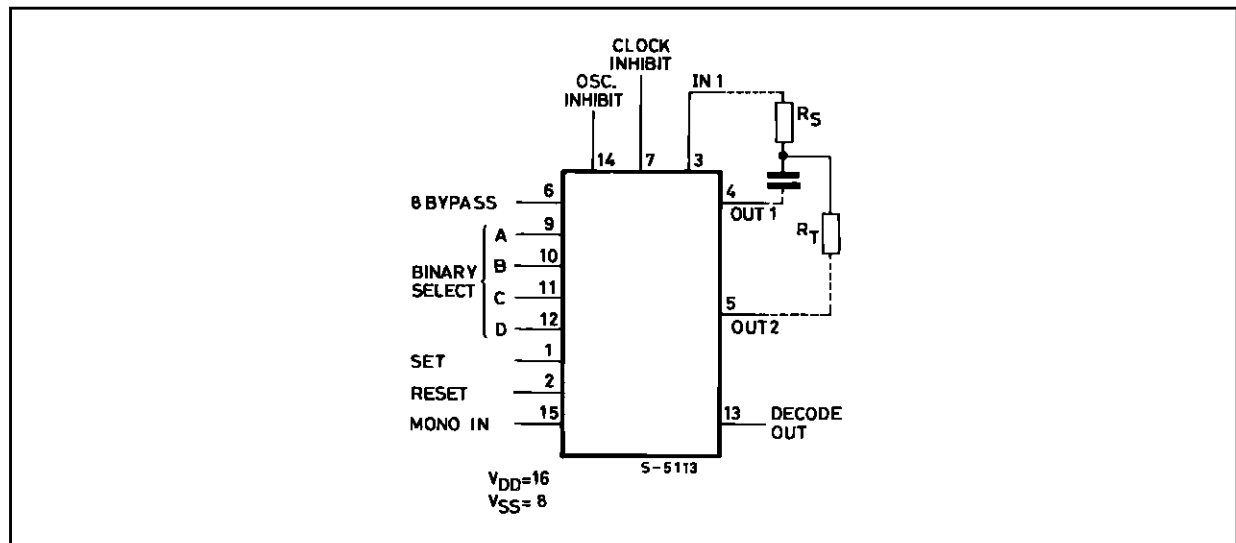


HCC/HCF4536B

Input IN1 serves as either the external clock input or the input to the on-chip RC oscillator. OUT1 and OUT2 are connection terminals for the external RC components. In addition, an on-chip monostable circuit is provided to allow a variable pulse width output. Various timing functions can be achieved using combinations of these capabilities. A logic 1 on the 8-BYPASS input enables a bypass of the first 8 stages and makes stage 9 the first counter stage of the last 16 stages. Selection of 1 of 16 outputs is accomplished by the decoder and the BCD inputs A, B, C

and D. MONO IN is the timing input for the on-chip monostable oscillator. Grounding of the MONO IN terminal through a resistor of 10K Ω or higher, disables the one-shot circuit and connects the decoder directly to the DECODE OUT terminal. A resistor to V_{DD} and a capacitor to ground from the MONO IN terminal enables the one-shot circuit and controls its pulse width. A fast test mode is enabled by a logic 1 on 8-BYPASS, SET, and RESET. This mode divides the 24-stage counter into three 8-stage sections to facilitate a fast test sequence.

FUNCTIONAL DIAGRAM



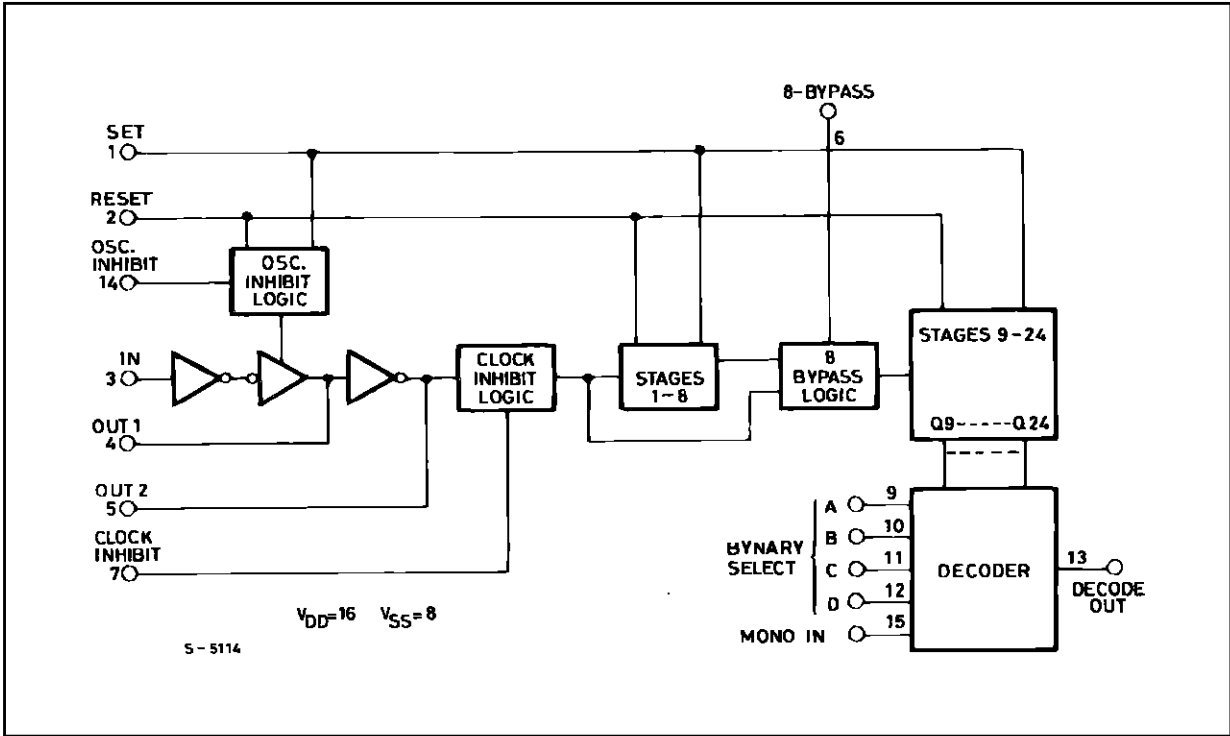
ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{DD} *	Supply Voltage : HCC Types HCF Types	– 0.5 to + 20 – 0.5 to + 18	V V
V _i	Input Voltage	– 0.5 to V _{DD} + 0.5	V
I _I	DC Input Current (any one input)	± 10	mA
P _{tot}	Total Power Dissipation (per package) Dissipation per Output Transistor for T _{op} = Full Package-temperature Range	200 100	mW mW
T _{op}	Operating Temperature : HCC Types HCF Types	– 55 to + 125 – 40 to + 85	°C °C
T _{stg}	Storage Temperature	– 65 to + 150	°C

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for external periods may affect device reliability.

* All voltages are with respect to V_{SS} (GND).

BLOCK DIAGRAM



TRUTH TABLE

In1	Set	Reset	Clock Inh	Osc Inh	Out1	Out2	Decode Out
	0	0	0	0			No Change
	0	0	0	0			Advance to Next State
X	1	0	0	0	0	1	1
X	0	1	0	0	0	1	0
X	0	0	1	0			No Change
0	0	0	0	X	0	1	No Change
1	0	0	0				Advance to Next State

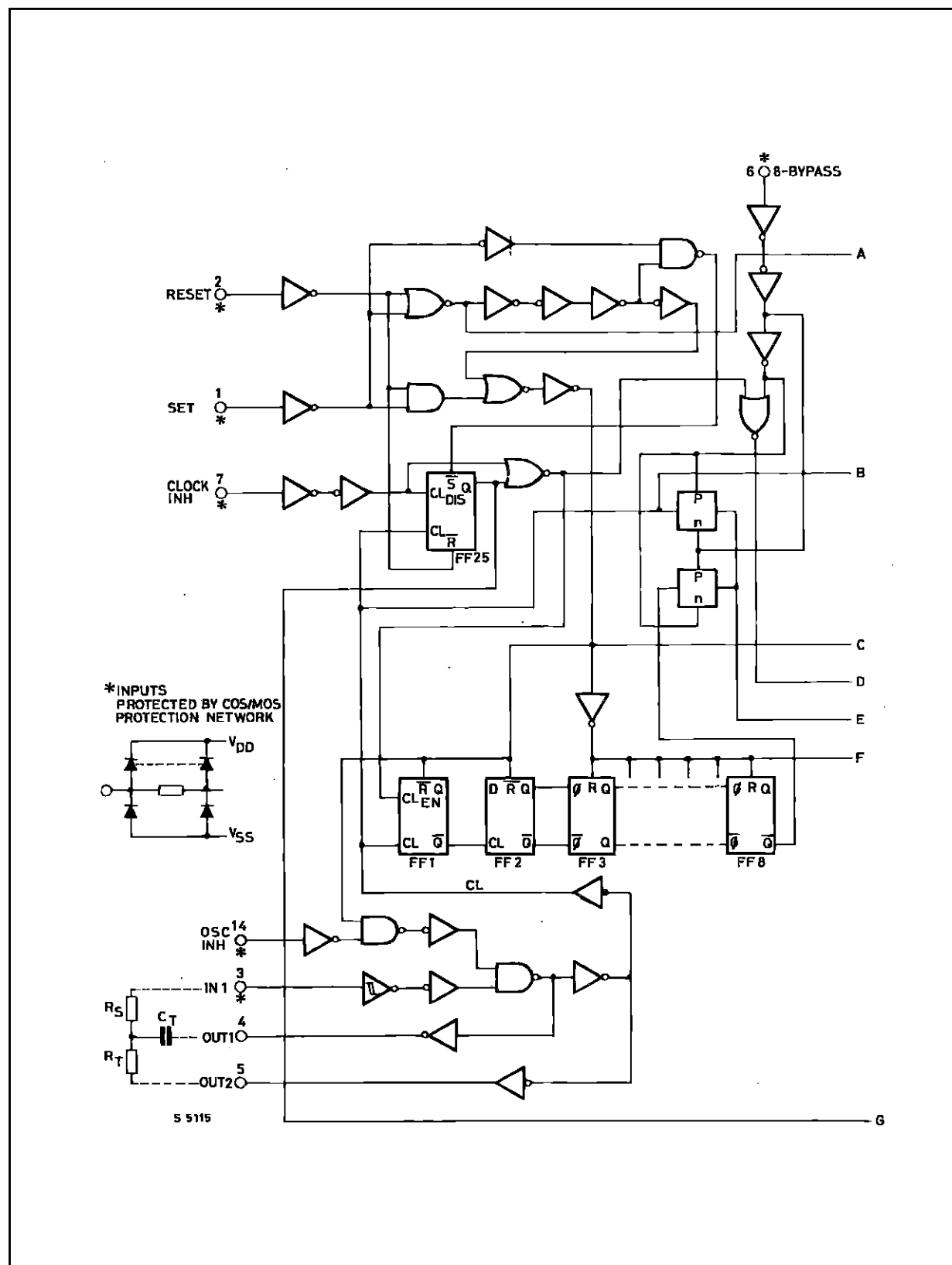
0 = Low Level

DECODE OUT SELECTION TABLE

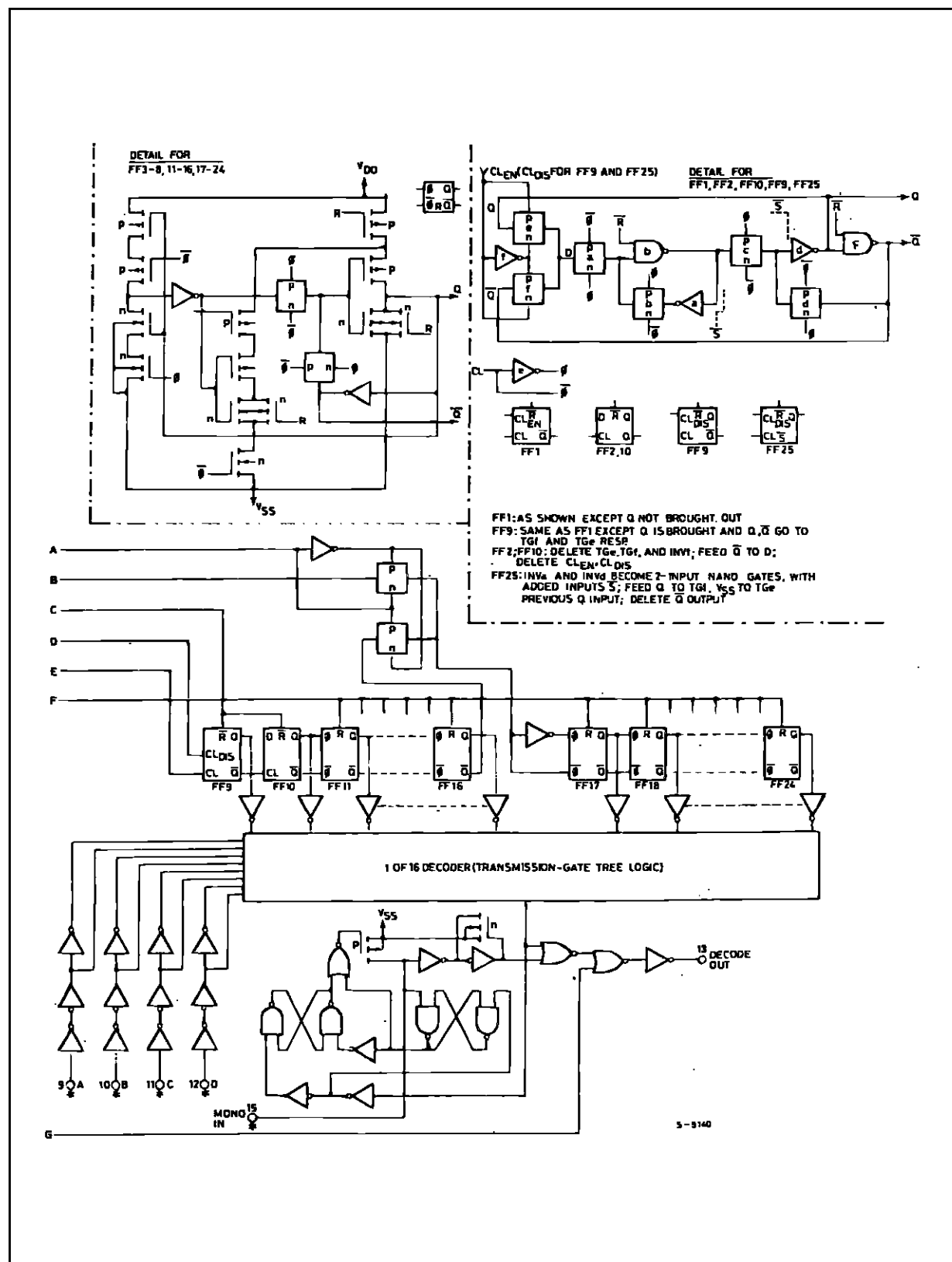
D	C	B	A	Number or Stages In Divider Chain	
				8-BYPASS = 0	8-BYPASS = 1
0	0	0	0	9	1
0	0	0	1	10	2
0	0	1	0	11	3
0	0	1	1	12	4
0	1	0	0	13	5
0	1	0	1	14	6
0	1	1	0	15	7
0	1	1	1	16	8
1	0	0	0	17	9
1	0	0	1	18	10
1	0	1	0	19	11
1	0	1	1	20	12
1	1	0	0	21	13
1	1	0	1	22	14
1	1	1	0	23	15
1	1	1	1	24	16

0 = Low Level

LOGIC DIAGRAMS (continued on next page)



LOGIC DIAGRAMS (continued)



STATIC ELECTRICAL CHARACTERISTICS (over recommended operating conditions)

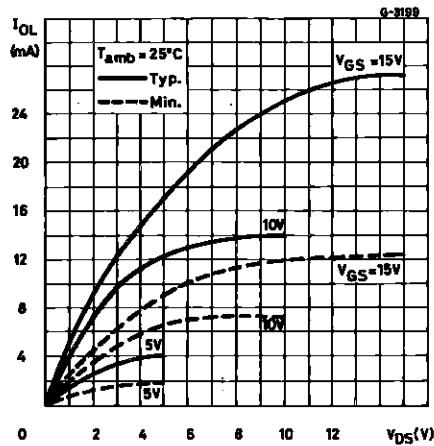
Symbol	Parameter		Test Conditions				Value						Unit	
			V _I (V)	V _O (V)	I _O (μA)	V _{DD} (V)	T _{Low} *		25°C			T _{High} *		
							Min.	Max.	Min.	Typ.	Max.	Min.		Max.
I _L	Quiescent Current	HCC Types	0/ 5			5		5		0.04	5		150	μA
			0/10			10		10		0.04	10		300	
			0/15			15		20		0.04	20		600	
			0/20			20		100		0.08	100		3000	
		HCF Types	0/ 5			5		20		0.04	20		150	
			0/10			10		40		0.04	40		300	
			0/15			15		80		0.04	80		600	
V _{OH}	Output High Voltage	0/ 5		< 1	5	4.95		4.95			4.95		V	
		0/10		< 1	10	9.95		9.95			9.95			
		0/15		< 1	15	14.95		14.95			14.95			
V _{OL}	Output Low Voltage	5/0		< 1	5		0.05			0.05		0.05	V	
		10/0		< 1	10		0.05			0.05		0.05		
		15/0		< 1	15		0.05			0.05		0.05		
V _{IH}	Input High Voltage		0.5/4.5	< 1	5	3.5		3.5			3.5		V	
			1/9	< 1	10	7		7			7			
			1.5/13.5	< 1	15	11		11			11			
V _{IL}	Input Low Voltage		4.5/0.5	< 1	5		1.5			1.5		1.5	V	
			9/1	< 1	10		3			3		3		
			13.5/1.5	< 1	15		4			4		4		
I _{OH}	Output Drive Current	HCC Types	0/ 5	2.5		5	− 2		− 1.6	− 3.2		− 1.15		mA
			0/ 5	4.6		5	− 0.64		− 0.51	− 1		− 0.36		
			0/10	9.5		10	− 1.6		− 1.3	− 2.6		− 0.9		
			0/15	13.5		15	− 4.2		− 3.4	− 6.8		− 2.4		
		HCF Types	0/ 5	2.5		5	− 1.53		− 1.36	− 3.2		− 1.1		
			0/ 5	4.6		5	− 0.52		− 0.44	− 1		− 0.36		
			0/10	9.5		10	− 1.3		− 1.1	− 2.6		− 0.9		
			0/15	13.5		15	− 3.6		− 3.0	− 6.8		− 2.4		
I _{OL}	Output Sink Current	HCC Types	0/ 5	0.4		5	0.64		0.51	1		0.36	mA	
			0/10	0.5		10	1.6		1.3	2.6		0.9		
			0/15	1.5		15	4.2		3.4	6.8		2.4		
		HCF Types	0/ 5	0.4		5	0.52		0.44	1		0.36		
			0/10	0.5		10	1.3		1.1	2.6		0.9		
			0/15	1.5		15	3.6		3.0	6.8		2.4		
I _{IH} , I _{IL}	Input Leakage Current	HCC Types	0/18	Any Input	18		± 0.1		±10 ^{−5}	± 0.1		± 1	μA	
		HCF Types	0/15		15		± 0.3		±10 ^{−5}	± 0.3		± 1		
C _I	Input Capacitance			Any Input					5	7.5			pF	

* T_{Low} = - 55°C for **HCC** device : - 40°C for **HCF** device.* T_{High} = + 125°C for **HCC** device : + 85°C for **HCF** device.The Noise Margin for both "1" and "0" level is : 1V min. with V_{DD} = 5V , 2V min. with V_{DD} = 10V, 2.5 V min. with V_{DD} = 15V.

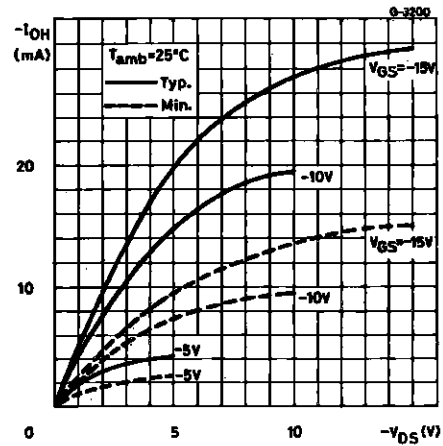
DYNAMIC ELECTRICAL CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, $C_L = 50\text{ pF}$, $R_L = 200\text{ K}\Omega$, typical temperature coefficient for all V_{DD} values is $03\text{ }^{\circ}\text{C}/^{\circ}\text{C}$, all input rise and fall times = 20 ns)

Symbol	Parameter	Test Conditions		Value			Unit
			V_{DD} (V)	Min.	Typ.	Max.	
t_{PLH} t_{PHL}	Propagation Delay Time Clock to Q1, 8-bypass High		5		1	2	μs
			10		0.5	1	
			15		0.35	0.7	
	Clock to Q1, 8-bypass Low		5		2.5	5	μs
			10		0.8	1.6	
			15		0.6	1.2	
	Clock to Q16		5		4	8	μs
			10		1.5	3	
			15		1	2	
	Q_n to Q_{n+1}		5		150	300	ns
			10		75	150	
			15		50	100	
t_{PLH}	Propagation Delay Time		5		300	600	ns
			10		125	250	
			15		80	160	
t_{PHL}	Reset to Q_n		5		3	6	μs
			10		1	2	
			15		0.75	1.5	
t_{TLH} t_{THL}	Transition Time		5		100	200	ns
			10		50	100	
			15		40	80	
t_w	Pulse Width Clock		5		200	400	ns
			10		75	150	
			15		50	100	
	Set		5		200	400	ns
			10		100	200	
			15		60	120	
	Reset		5		3	6	μs
			10		1	2	
			15		0.75	1.5	
	Recovery Time Set		5		2.5	5	μs
			10		1	2	
			15		0.6	1.6	
	Reset		5		3.5	7	μs
			10		1.5	3	
			15		1	2	
t_r, t_f	Clock Input Rise or Fall Time		5	Unlimited			μs
			10				
			15				
f_{CL}	Maximum Clock Input Frequency			0.5	1		MHz
				10	3		
				15	5		

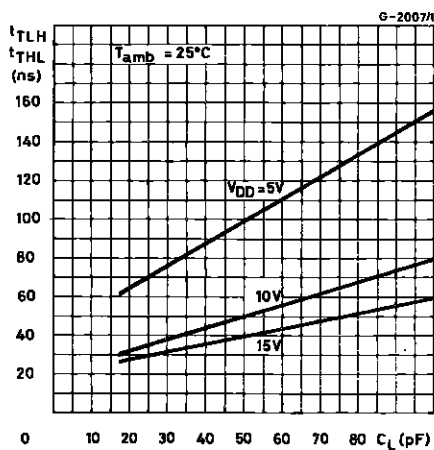
Output Low (sink) Current Characteristics.



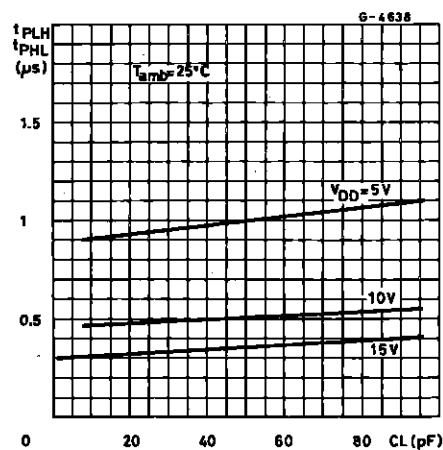
Output High (source) Current Characteristics.



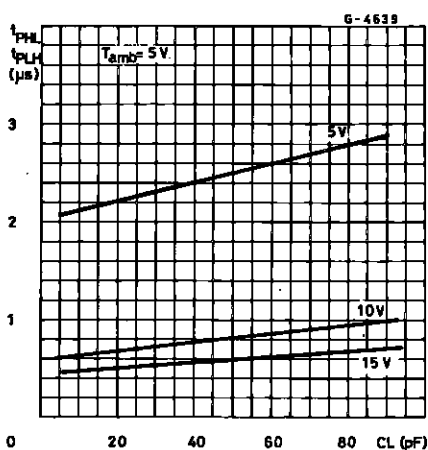
Typical Transition Time vs. Load Capacitance.



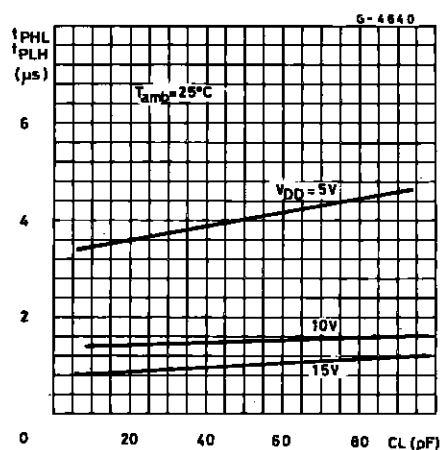
Typical Propagation Delay Time vs. Load Capacitance (clock to Q1, 8 Bypass high).



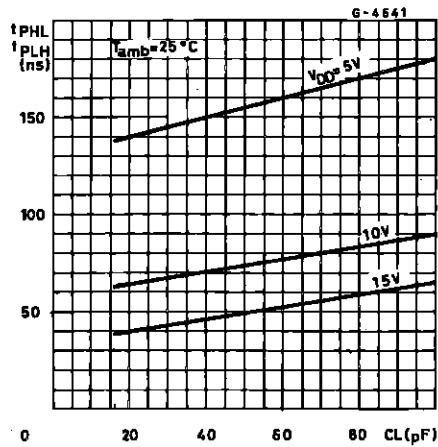
Typical Propagation Delay Time vs. Load Capacitance (Clock to Q1, 8 Bypass low).



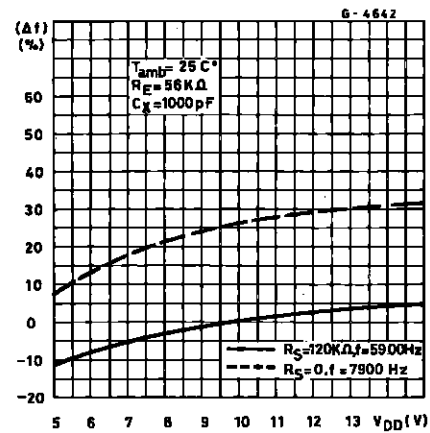
Typical Propagation Delay Time vs. Load Capacitance (Clock to Q16, 8 Bypass high).



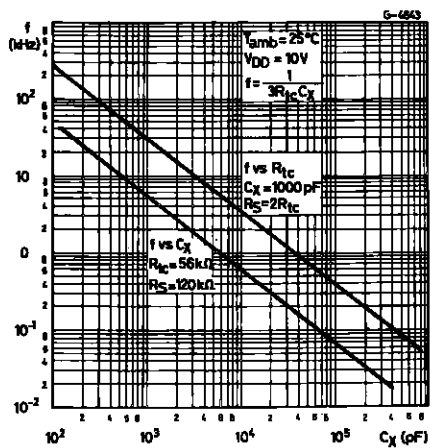
Typical Propagation Delay Time vs. Load Capacitance (Q_N to Q_{N+1}).



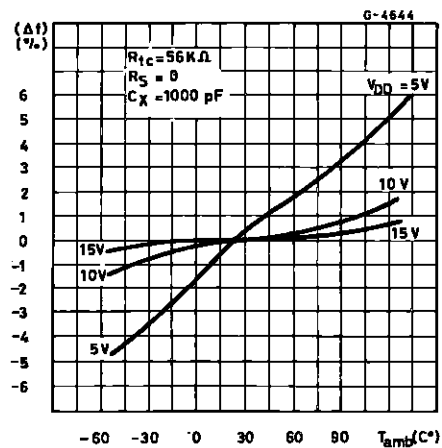
Typical RC Oscillator Frequency Deviation vs. Supply Voltage.



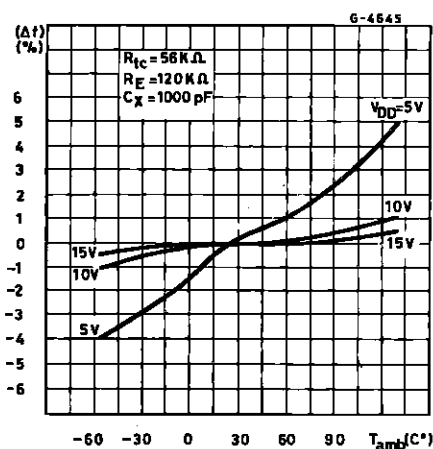
Typical RC Oscillator Frequency Deviation vs. Time Constant Resistance and Capacitance.



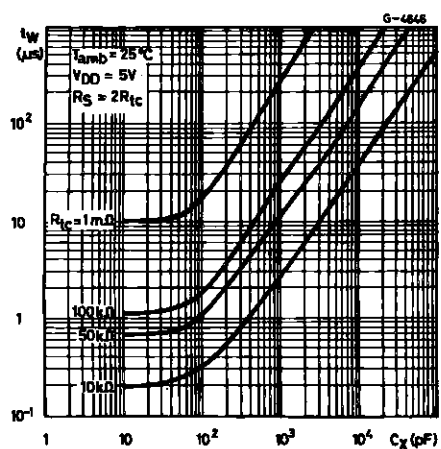
Typical RC Oscillator Frequency Deviation vs. Ambient Temperature ($R_S = 0$).



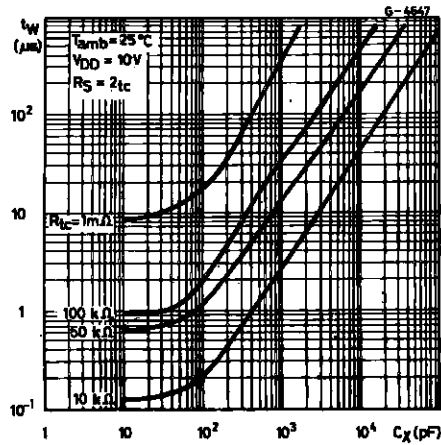
Typical RC Oscillator Frequency Deviation vs. Ambient Temperature ($R_S = 120\text{K}\Omega$).



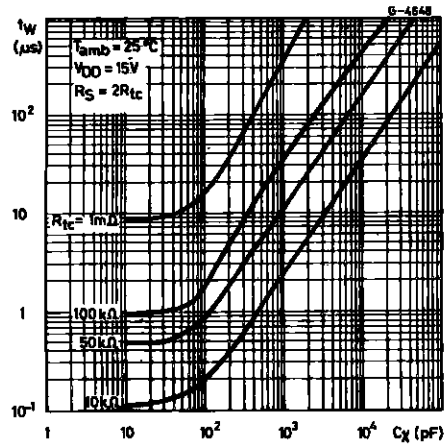
Typical Pulse Width vs. External Capacitance ($V_{DD} = 5\text{V}$).



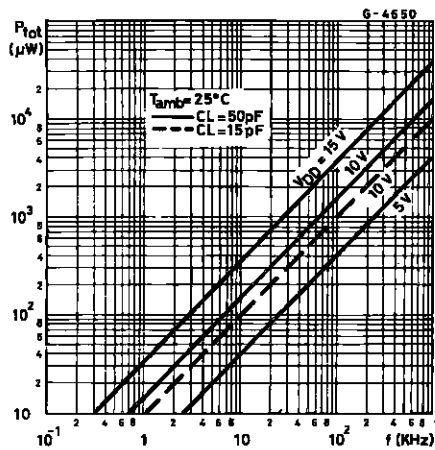
Typical Pulse Width vs. External Capacitance ($V_{DD} = 10V$).



Typical Pulse Width vs. External Capacitance ($V_{DD} = 15V$).

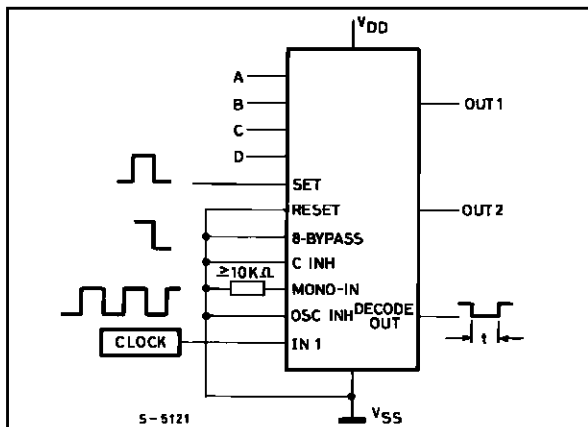


Typical Dynamic Power Dissipation vs. Input Pulse Frequency.

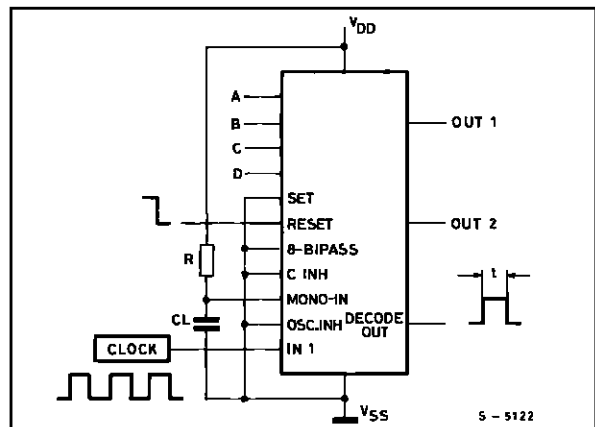


TYPICAL APPLICATIONS

Time Internal Configuration Using External Clock ; Set and Clock Inhibit Functions.

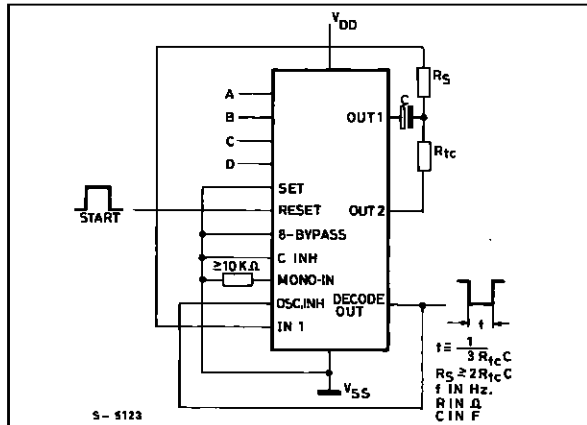


Time Internal Configuration Using External Clock ; Reset and Output Monostable to Achieve a Pulse Output.

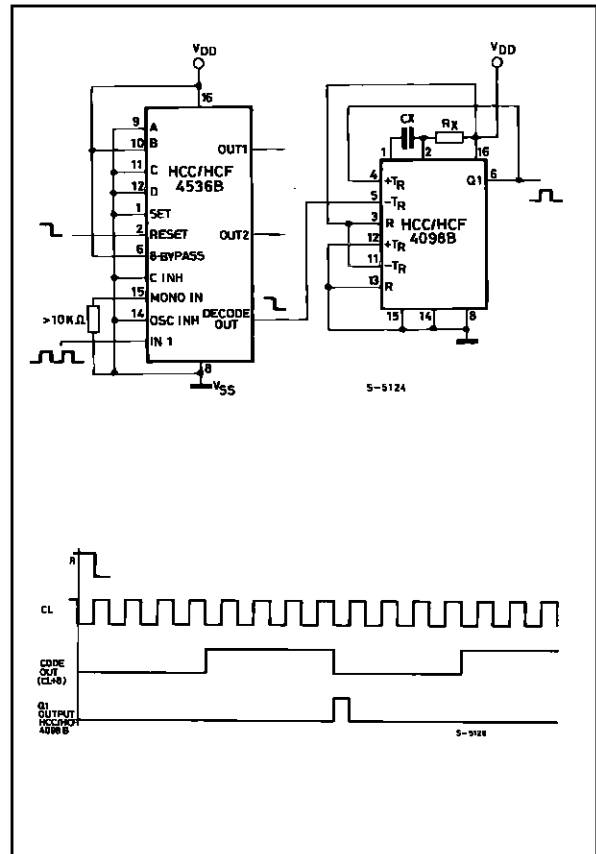


TYPICAL APPLICATIONS (Continued)

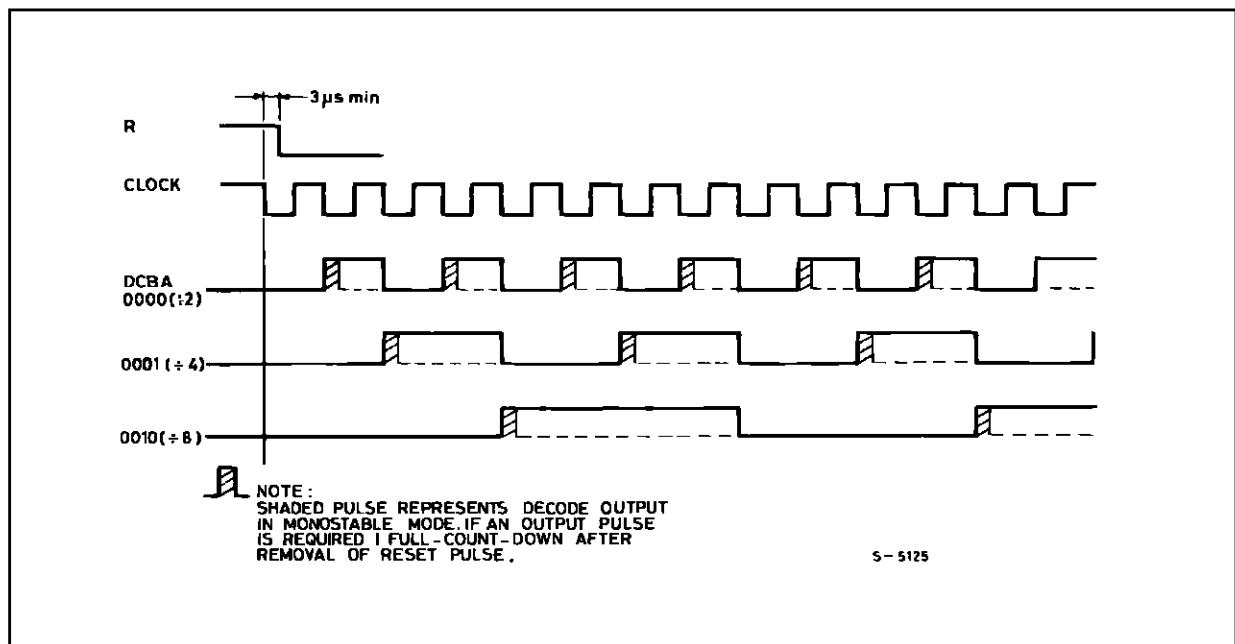
Time Interval Configuration Using Onchip RC Oscillator and Reset Input to Initiate Time Interval.



Application Showing Use of 4098B and 4536B to get Decode Pulse 8 Clock Pulses after Reset



TIMING DIAGRAM



Functional Test Sequence					
Inputs				Outputs	Comments
In1	Set	Reset	8-Bypass	Decade Out Q1 Thru Q24	All 24 steps are in reset mode.
1	0	1	1	0	Counter is in three 8-stage section in parallel mode. First "1" to "0" Transition of Clock
1	1	1	1	0	
0	1	1	1	0	
1 0 — —	1	1	1		255 "1" to "0" transitions are clocked in the counter.
0	1	1	1	1	The 255 "1" to "0" Transition
0	0	0	0	1	Counter converted back to 24 stages in series mode. Set and Reset must be connected together and simultaneously go from "1" to "0".
1	0	0	0	1	In ₁ switches to a "1".
0	0	0	0	0	Counter Ripples from an all "1" state to an all "0" state.

FUNCTIONAL TEST SEQUENCE

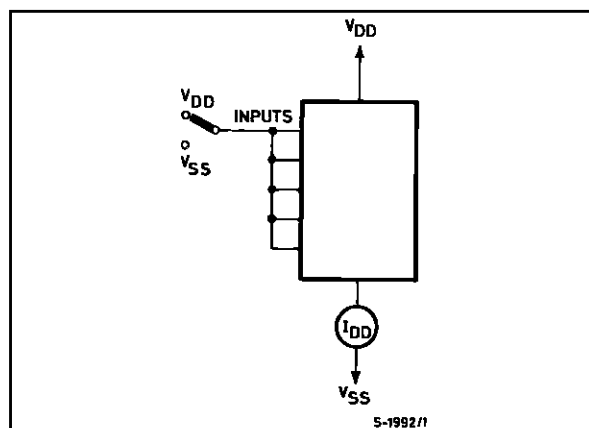
Test Function has been included for the reduction of test time required to exercise all 24 counter stages.

This test function divides the counter into three 8-stage section and 255 counts are loaded in each of the 8-stage sections in parallel. All flip-flops are now

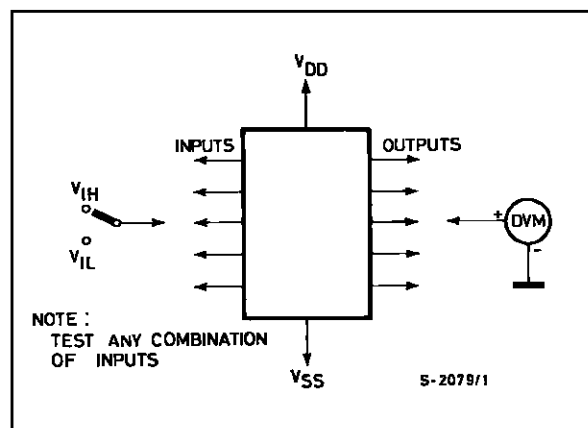
at a "1". The counter is now returned to the normal 24-steps in series configuration. One more pulse is entered into In₁ which will cause the counter to ripple from an all "1" state to an all "0" state.

TEST CIRCUITS

Quiescent Device Current.

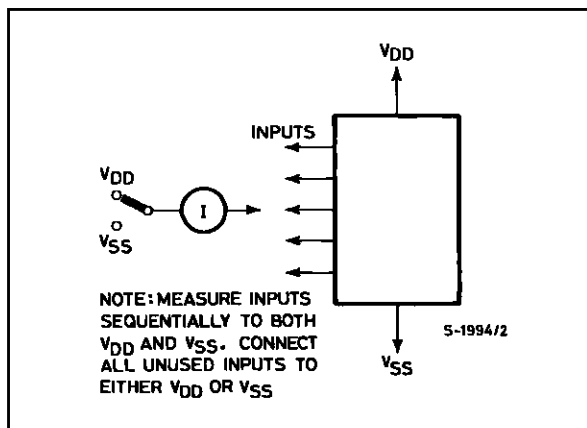


Input Voltage.

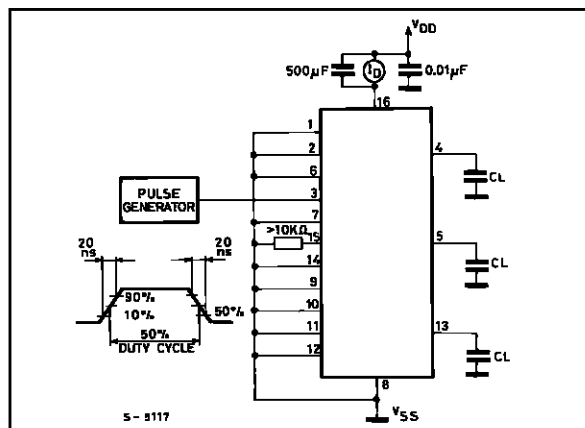


TEST CIRCUITS (continued)

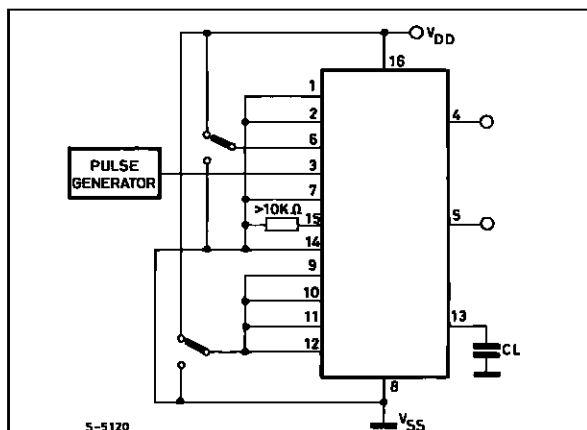
Input Leakage Current.



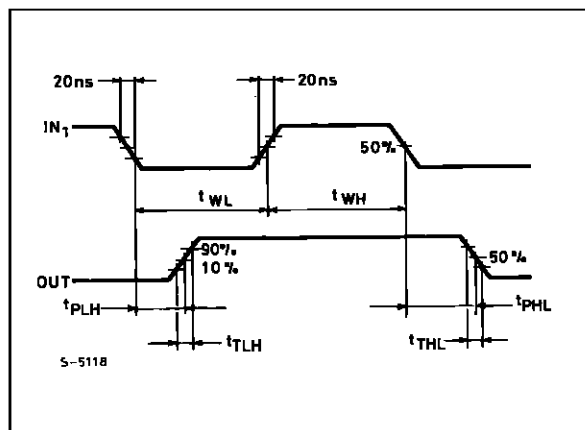
Dynamic Power Dissipation.



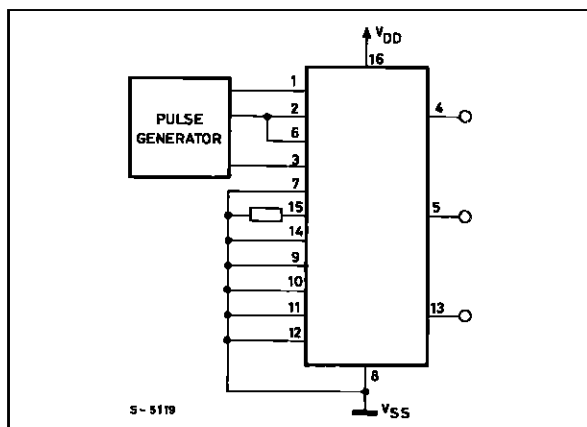
Switching Time.



Input Waveforms for Switching-Time.

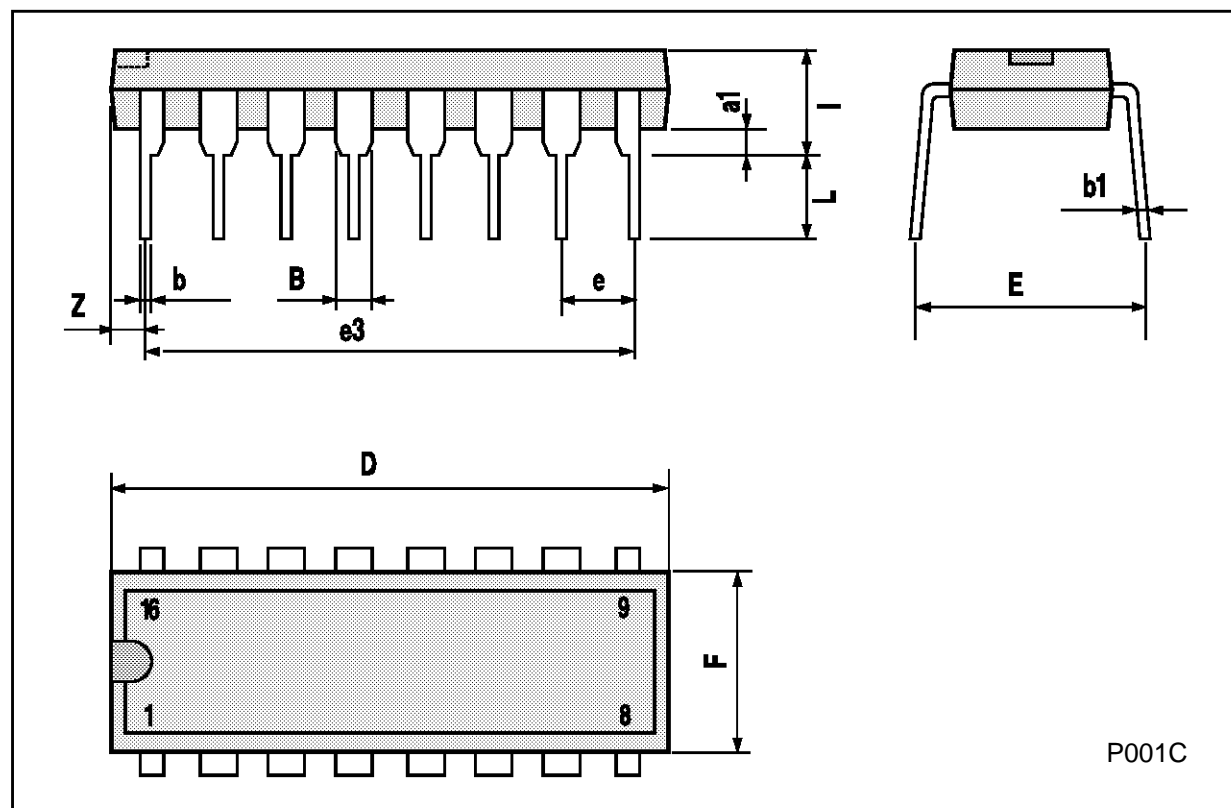


Functional.



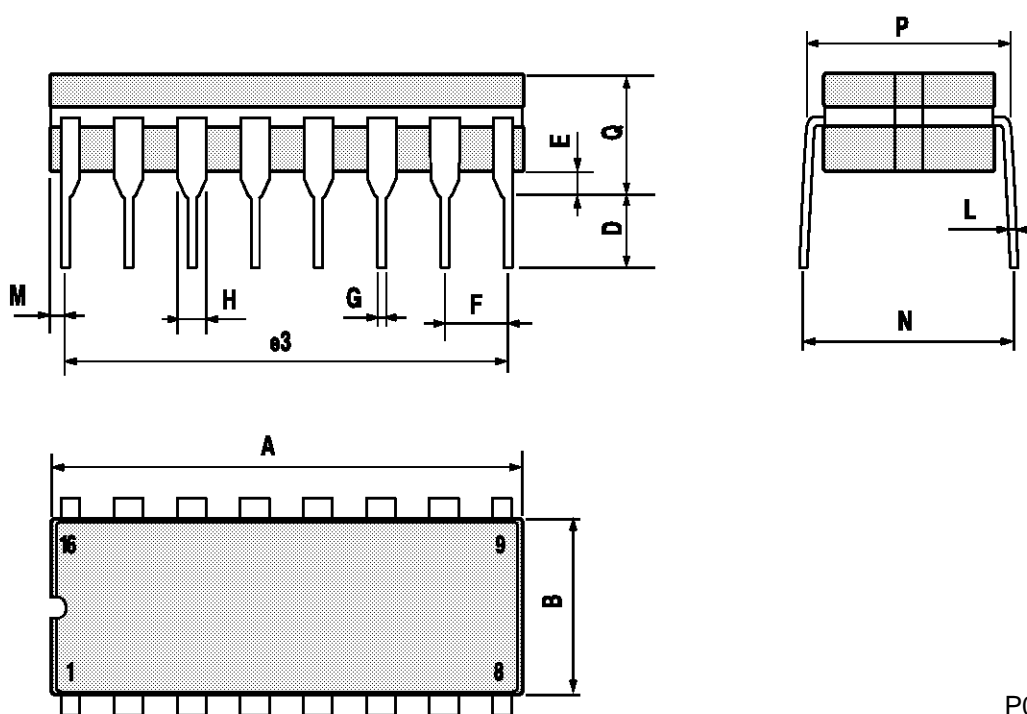
Plastic DIP16 (0.25) MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
a1	0.51			0.020		
B	0.77		1.65	0.030		0.065
b		0.5			0.020	
b1		0.25			0.010	
D			20			0.787
E		8.5			0.335	
e		2.54			0.100	
e3		17.78			0.700	
F			7.1			0.280
I			5.1			0.201
L		3.3			0.130	
Z			1.27			0.050



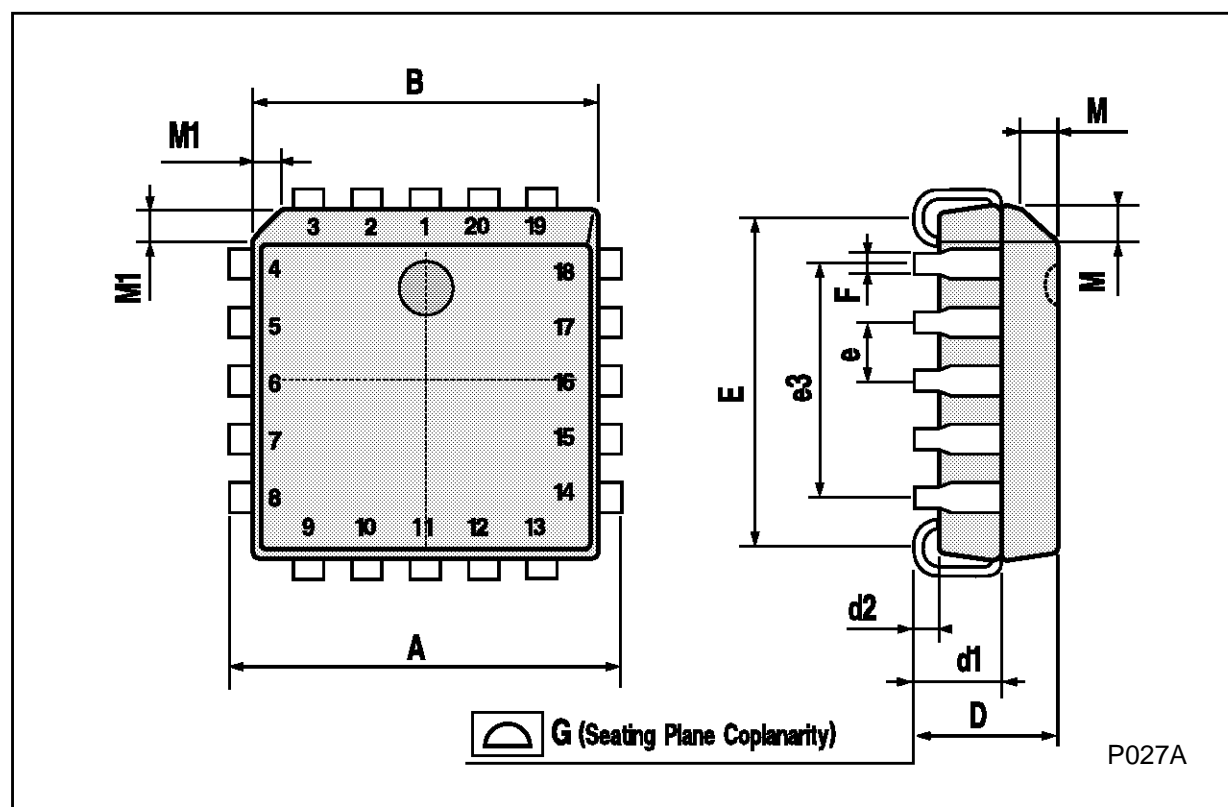
Ceramic DIP16/1 MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			20			0.787
B			7			0.276
D		3.3			0.130	
E	0.38			0.015		
e3		17.78			0.700	
F	2.29		2.79	0.090		0.110
G	0.4		0.55	0.016		0.022
H	1.17		1.52	0.046		0.060
L	0.22		0.31	0.009		0.012
M	0.51		1.27	0.020		0.050
N			10.3			0.406
P	7.8		8.05	0.307		0.317
Q			5.08			0.200



PLCC20 MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	9.78		10.03	0.385		0.395
B	8.89		9.04	0.350		0.356
D	4.2		4.57	0.165		0.180
d1		2.54			0.100	
d2		0.56			0.022	
E	7.37		8.38	0.290		0.330
e		1.27			0.050	
e3		5.08			0.200	
F		0.38			0.015	
G			0.101			0.004
M		1.27			0.050	
M1		1.14			0.045	



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